

INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>				Docket Number (Optional) 1109.005		Application Number		
				Applicant(s) Eichelberger et al.				
				Filing Date Herewith		Group Art Unit		
U.S. PATENT DOCUMENTS								
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
MDP	AA	5,841,193	11/24/98	Eichelberger et al.	257	723	#2	
FOREIGN PATENT DOCUMENTS								
	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO
OTHER DOCUMENTS <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>								
MDP	AB	'EPIC CSP Assembly and Reliability Methods,' James E. Kohl et al., originally published in the Proceedings of CS198, Santa Clara, California, May 1998.						
MDP	AC	'Low Cost Chip Scale Packaging and Interconnect Technology,' James E. Kohl, et al., originally published in the Proceedings of the Surface Mount International Conference, San Jose, California, September 1997.						
EXAMINER <i>Harold D. Riegel Jr.</i>				DATE CONSIDERED <i>6/8/2001</i>				